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U.S. DEPARTMENT OF COMMERCE Form PTO-1449 PATENT AND TRADEMARK OFFICE ATTY. DOCKET NO. MI22-2194

SERIAL NO. 10/636,038

LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)

APPLICANT: Gurtej S. Sandhu

FILING DATE August 6, 2003

GROUP 2824

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

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LIST OF ART CITED BY APPLICANT (Use several sheets if accessary) FILING DATE August 6, 2003 2812 U.S. PATENT DOCUMENTS Date Name Chan Subclass Filing Date If Appropriate Document 12/17/2002 6,495,436 Ahn et al. AA 6,762,114 7/13/2004 Chambers AB 6,717,226 4/6/2004 Hedge et al. AC 6,608,378 8/19/2003 Ahn et al. AD 6/17/2003 6,579,767 Park et al. AE 2/25/2003 6,524,918 Park et al. AF 2004/0023462 2/5/2004 Rotondaro et al. AG 2003/0232506 12/18/2003 Metzner et al. Ev372467864 ΑH 2001/0029092 10/11/2003 Park et al. ΑĬ EP 2001/0024860 9/27/2001 Park et al. ΑJ AK AL FUREIGN PATENT DOCUMENTS Subclass Translation Document Number Date Country AM ٨N ΑO AP ΛQ OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) "Surface preparation and post thermal treatment effects on interface properties of thin AL403 films deposited by ALD;" Chang et al.: Microelectronic Engineering 72, 2004; рр. 326-331. "Effect Purge time on the properties of HfO2 films prepared by atomic layer deposition;" Kawahara et al.: IELEEJ Transactions on Electronics; Vol. E87-C. No. 1; January 2004; pp. 2-8. "High-kmaterials for advanced gate stack dielectrics: a comparison of ALCVD and MOCVD as deposition technologics;" Caymax et al.: CMOS Front-End materials and Process Technology Symposium (Mater. Res. Soc. Symposium Proceedings Vol. 765); April 22-24, 2003; 47-58 DATE CONSIDERED EXAMINER *EVAMINER: Initial if reference considered, whether or not citation is in conforman

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